

BTA40, **BTA41**, **BTB41**

40 A standard TRIACs

Features

- High current TRIAC
- Low thermal resistance with clip bonding
- High commutation capability
- BTA series UL1557 certified (File ref: 81734)
- Packages are RoHS (2002/95/EC) compliant

Applications

- On/off function in static relays, heating regulation, induction motor starting circuits
- Phase control operations in light dimmers, motor speed controllers, and similar

Description

Available in high power packages, the BTA/BTB40-41 series is suitable for general purpose AC switching.

The BTA series provides an insulated tab (rated at 2500 V rms).

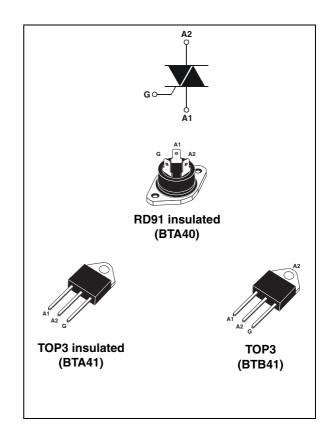


Table 1. Device summary

Symbol	Parameter	BTA40 ⁽¹⁾	BTA41 ⁽¹⁾	BTB41	Unit
I _{T(RMS)}	On-state rms current	40	41	41	Α
V _{DRM} /V _{RRM}	Repetitive peak off-state voltage	600 and 800	600 and 800	600 and 800	V
I _{GT}	Triggering gate current	50	50	50	mA

^{1.} Insulated package

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1 Characteristics

Table 2. Absolute maximum ratings

Symbol	Parameter			Value	Unit	
1	On-state rms current	TOP3 $T_c = 95 ^{\circ}C$		40	Α	
I _{T(RMS)}	(full sine wave)	RD91 / TOP ins.	T _c = 80 °C	40	A	
	Non repetitive surge peak on-state	F = 50 Hz	t = 20 ms	400	А	
I _{TSM}	current (full cycle, T _j initial = 25 °C)	F = 60 Hz	t = 16.7 ms	420		
l ² t	I ² t Value for fusing	t _p = 10 ms		1000	A ² s	
dI/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $t_r \le 100 \text{ ns}$	F = 120 Hz		50	A/μs	
V _{DSM} /V _{RSM}	Non repetitive surge peak off-state voltage	tate $t_p = 10 \text{ ms}$ $T_j = 25 \text{ °C}$		V _{DSM} /V _{RSM} + 100	V	
I _{GM}	Peak gate current $t_p = 20 \mu s$ $T_j = 125 ^{\circ}C$		8	Α		
P _{G(AV)}	Average gate power dissipation $T_j = 125 ^{\circ}\text{C}$		1	W		
T _{stg} T _j	Storage junction temperature range Operating junction temperature range			- 40 to + 150 - 40 to + 125	°C	

Table 3. Electrical characteristics ($T_j = 25$ °C, unless otherwise specified)

Symbol	Parameter			Value	Unit
I _{GT} ⁽¹⁾	$V_D = 12 \text{ V}$ $R_L = 33 \Omega$	I - II - III IV	MAX.	50 100	mA
V _{GT}		ALL	MAX.	1.3	V
V_{GD}	$V_D = V_{DRM}$ $R_L = 3.3 \text{ k}\Omega$ $T_j = 125 \text{ °C}$	ALL	MIN.	0.2	V
I _H (2)	I _T = 500 mA		MAX.	80	mA
IL	1 121		MAX.	70	mA
'L	$I_{G} = 1.2 I_{GT}$	II	IVIAA.	160	lii.
dV/dt ⁽²⁾	V _D = 67% V _{DRM} gate open	T _j = 125 °C	MIN.	500	V/µs
(dV/dt)c ⁽²⁾	(dl/dt)c = 20 A/ms	T _j = 125 °C	MIN.	10	V/µs

^{1.} Minimum $I_{\mbox{\scriptsize GT}}$ is guaranted at 5% of $I_{\mbox{\scriptsize GT}}$ max.

^{2.} for both polarities of A2 referenced to A1

Table 4. Static characteristics

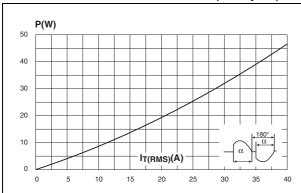
Symbol	Test conditions			Value	Unit
V _T ⁽¹⁾	$I_{TM} = 60 \text{ A}$ $t_p = 380 \mu\text{s}$	T _j = 25 °C	MAX.	1.55	V
V _{t0} (2)	Threshold voltage	T _j = 125 °C	MAX.	0.85	V
R _d ⁽²⁾	Dynamic resistance	T _j = 125 °C	MAX.	10	mΩ
I _{DRM}	V - V	T _j = 25 °C	MAX.	5	μΑ
I _{RRM}	$V_{DRM} = V_{RRM}$	T _j = 125 °C	IVIAA.	5	mA

^{1.} Minimum $I_{\mbox{\scriptsize GT}}$ is guaranted at 5% of $I_{\mbox{\scriptsize GT}}$ max.

Table 5. Thermal resistance

Symbol	Test conditions		Value	Unit
D	Junction to case (AC)	RD91 (insulated) / TOP3 insulated	0.9	°C/W
R _{th(j-c)}	Junction to case (AO)	TOP3	0.6	C/VV
R _{th(j-a)}	Junction to ambient	Junction to ambient TOP3 / TOP3 insulated		°C/W

Figure 1. Maximum power dissipation versus Figure 2. On-state rms current versus case on-state rms current (full cycle) temperature (full cycle)



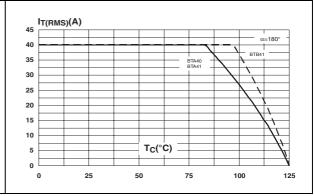


Figure 3. Relative variation of thermal impedance versus pulse duration

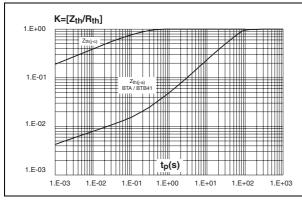
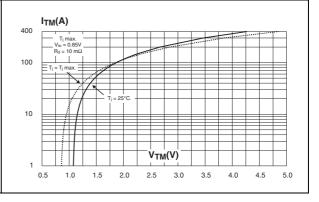


Figure 4. On-state characteristics (maximum values)



^{2.} for both polarities of A2 referenced to A1

Surge peak on-state current versus Figure 6. Figure 5. number of cycles

Non-repetitive surge peak on-state current for a sinusoidal pulse and corresponding value of I²t

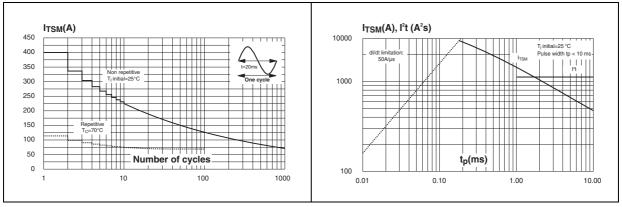
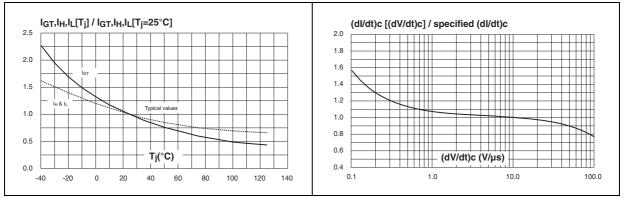
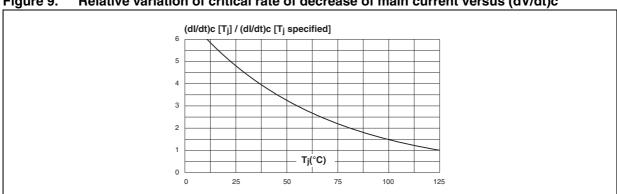


Figure 7. Relative variation of gate trigger, holding and latching current versus junction temperature

Figure 8. Relative variation of critical rate of decrease of main current versus (dV/dt)c (typical values)



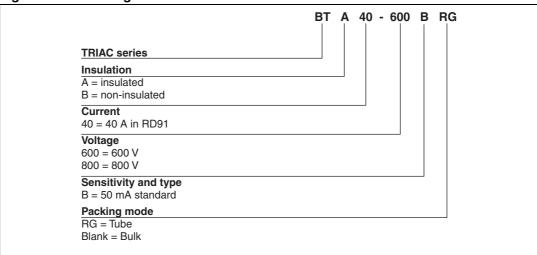
Relative variation of critical rate of decrease of main current versus (dV/dt)c Figure 9.



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2 Ordering information scheme

Figure 10. Ordering information scheme





3 Package information

- Epoxy meets UL94, V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK $^{\otimes}$ packages, depending on their level of environmental compliance. ECOPACK $^{\otimes}$ specifications, grade definitions and product status are available at: www.st.com. ECOPACK $^{\otimes}$ is an ST trademark.

Table 6. TOP3 insulated and non-insulated dimensions

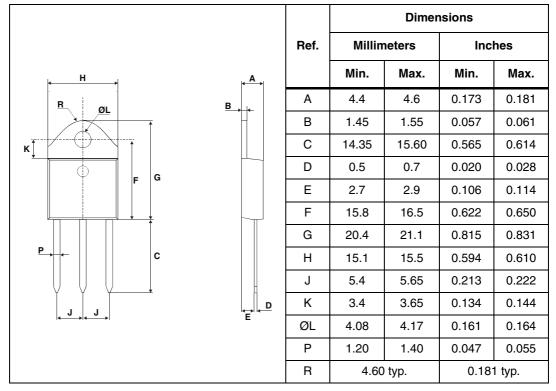
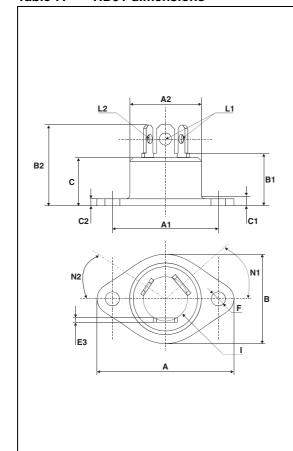


Table 7. RD91 dimensions



	Dimensions				
Ref.	Millin	neters	Inc	hes	
	Min.	Max.	Min.	Max.	
Α	-	40.00	-	1.575	
A1	29.90	30.30	1.177	1.193	
A2	-	22.00	-	0.867	
В	-	27.00	-	1.063	
B1	13.50	16.50	0.531	0.650	
B2	-	24.00	-	0.945	
С	-	14.00	-	0.551	
C1	-	3.50	-	0.138	
C2	1.95	3.00	0.077	0.118	
E3	0.70	0.90	0.027	0.035	
F	4.00	4.50	0.157	0.177	
I	11.20	13.60	0.441	0.535	
L1	3.10	3.50	0.122	0.138	
L2	1.70	1.90	0.067	0.075	
N1	33°	43°	33°	43°	
N2	28°	38°	28°	38°	

4 Ordering information

Table 8. Ordering information

Order code ⁽¹⁾	Marking	Package	Weight	Base qty	Delivery mode
BTA40-xxxB	BTA40xxxB	RD91	20 g	25	Bulk
BTA41-xxxBRG	BTA41xxxB	TOP3 Ins.	4.5 g	30	Tube
BTB41-xxxBRG	BTB41xxxB	TOP3	4.5 g	30	Tube

^{1.} xxx = voltage

5 Revision history

Table 9. Document revision history

Date	Revision Changes	
Sep-2003	5	Last update.
25-Mar-2005	6	TOP3 delivery mode changed from bulk to tube.
14-Oct-2005	7	${\rm T_{c}}$ values for ${\rm I_{T}}$ changed in Table 3. ECOPACK statement added.
10-Aug-2009	8	Updated <i>Table 2</i> to correctly place packages. Updated <i>Figure 2. Table 5</i> changed to correctly place TOP3. Updated ECOPACK statement.

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